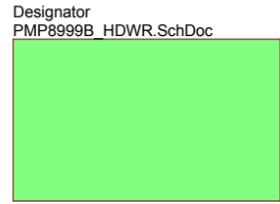
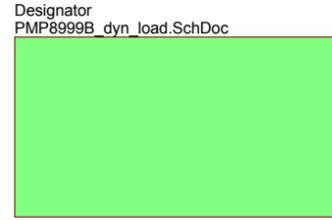
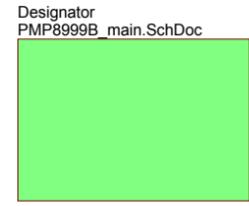


Revision History	
Revision	Notes

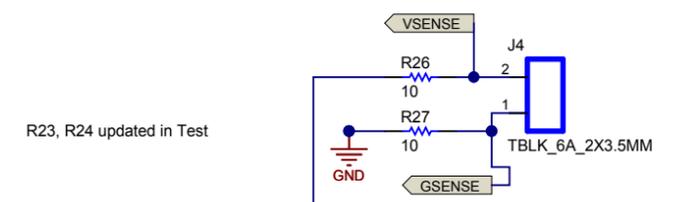
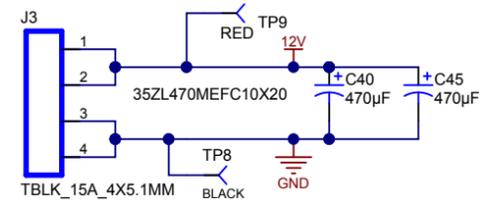
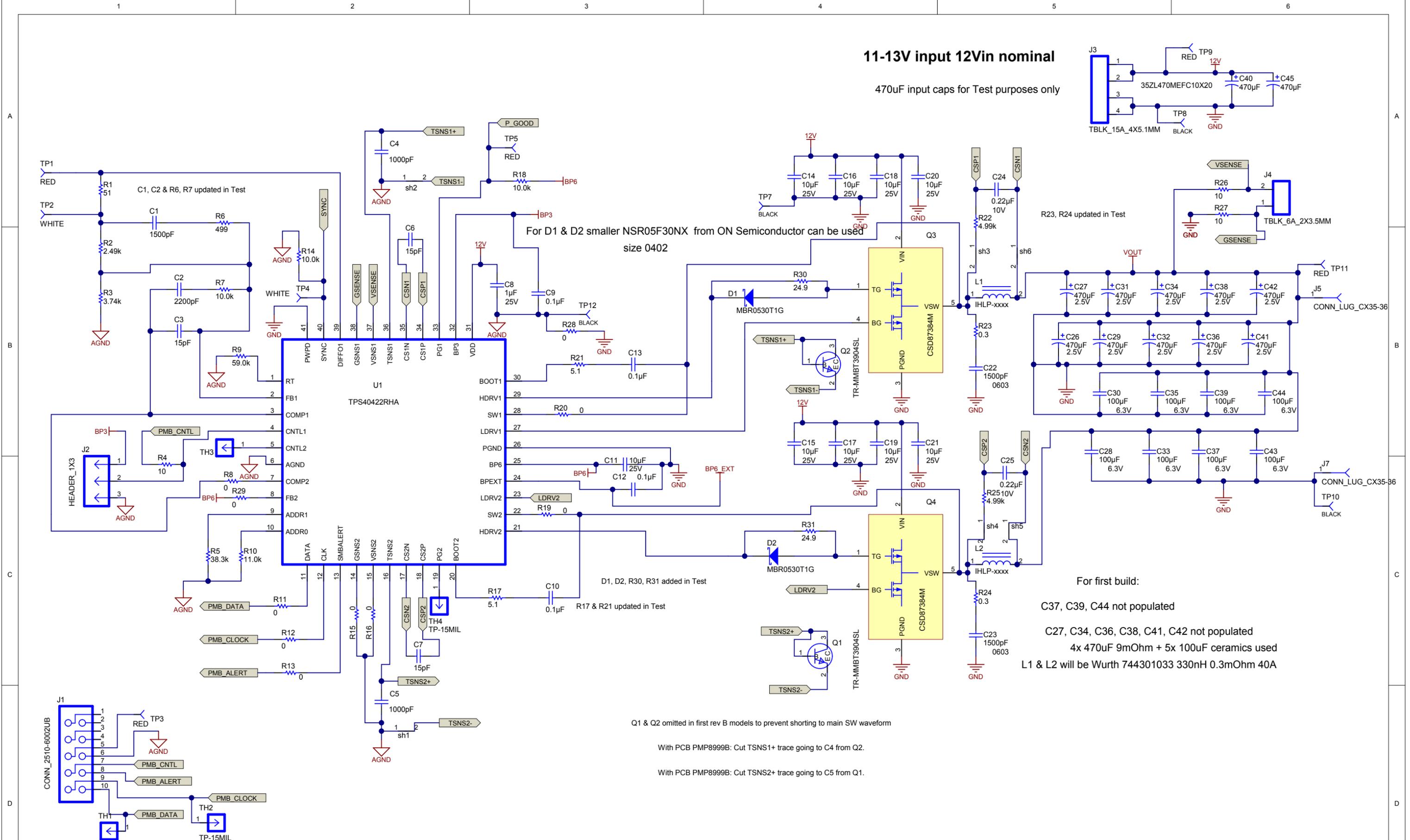


Place Block Diagram here (if appropriate) or delete this text box.
 If using a block diagram from another tool, save the picture as a .bmp
 file.
 Then, use menu Place|Drawing Tools|Graphic to insert the .bmp file
 on the schematic.

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Number: PMP8999	Rev: B	Designed for: Public Release	Mod. Date: 9/3/2013
SVN Rev: Not in version control	Assembly Variant: 001	Project Title: TPS40422 & CSD87384 2 Phases	Sheet: 1 of 4
Drawn By:	File: PMP8999B_cover.SchDoc	Sheet Title:	Size: B
Engineer: Josh Mandelcorn	Contact: http://www.ti.com/support		





For first build:
C37, C39, C44 not populated
C27, C34, C36, C38, C41, C42 not populated
4x 470uF 9mOhm + 5x 100uF ceramics used
L1 & L2 will be Wurth 744301033 330nH 0.3mOhm 40A

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Number: PMP8999	Rev: B	Designed for: Public Release	Mod. Date: 11/22/2013
SVN Rev: Not in version control	Assembly Variant: 001	Project Title: TPS40422 & CSD87384 2 Phases	Sheet Title:
Drawn By:	File: PMP8999B_main_SchDoc	Sheet: 2 of 4	Size: B
Engineer: Josh Mandelcorn	Contact: http://www.ti.com/support		





PCB Number: PMP8999
PCB Rev: B

PCB
LOGO
Texas Instruments



LBL1
PCB Label
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

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Designed for: Public Release		Mod. Date: 9/3/2013	
Project Title: TPS40422 & CSD87384 2 Phases			
Number: PMP8999	Rev: B	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: 001	Sheet: 4 of 4	
Drawn By:	File: PMP8999B_HDWR_SchDoc	Size: B	
Engineer: Josh Mandelcorn	Contact: http://www.ti.com/support		



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